

FIG. 1A

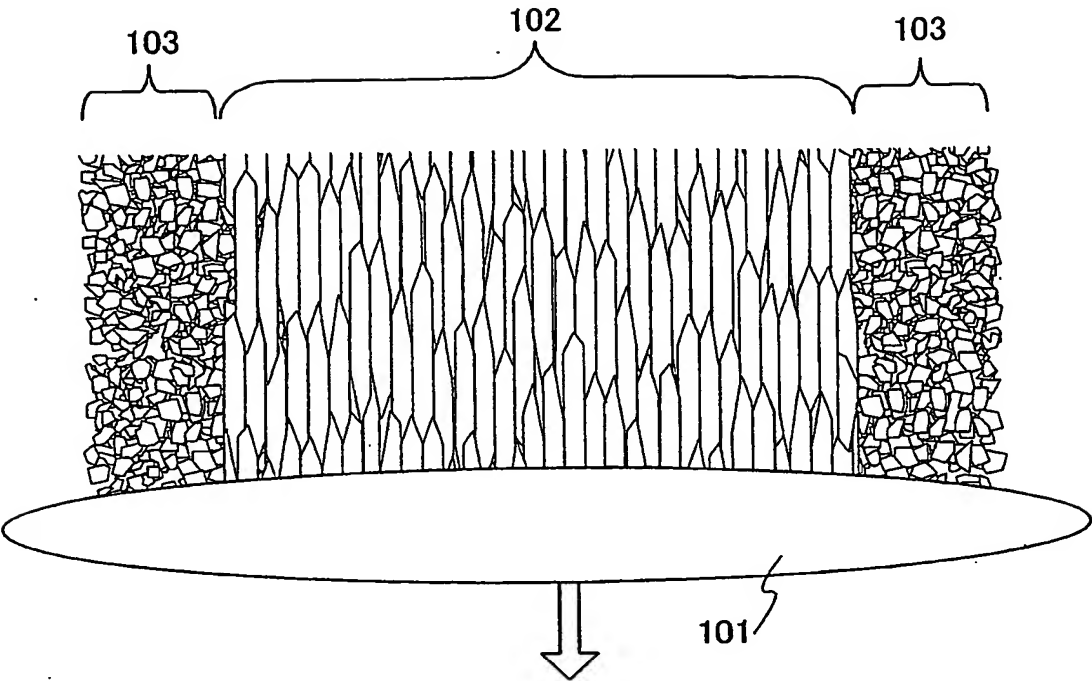


FIG. 1B

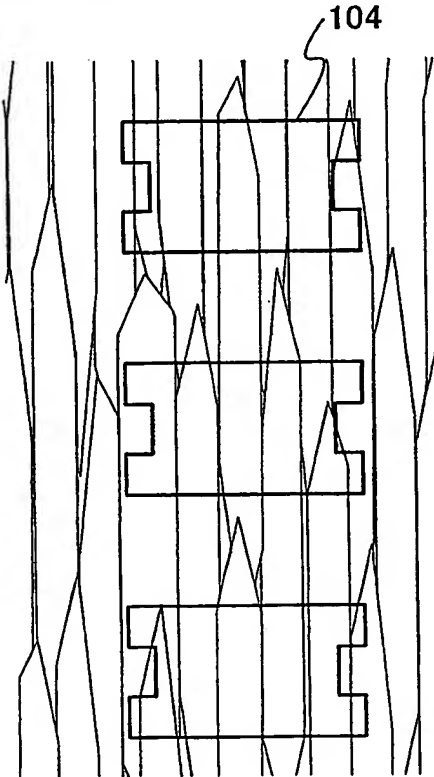
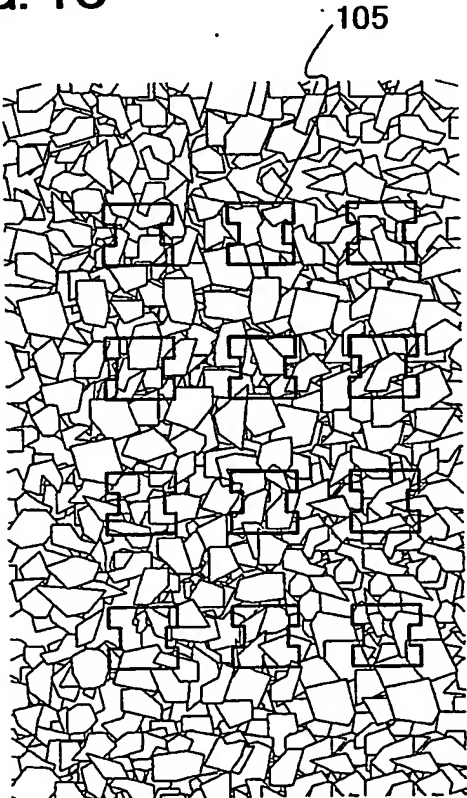


FIG. 1C



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FIG. 2A

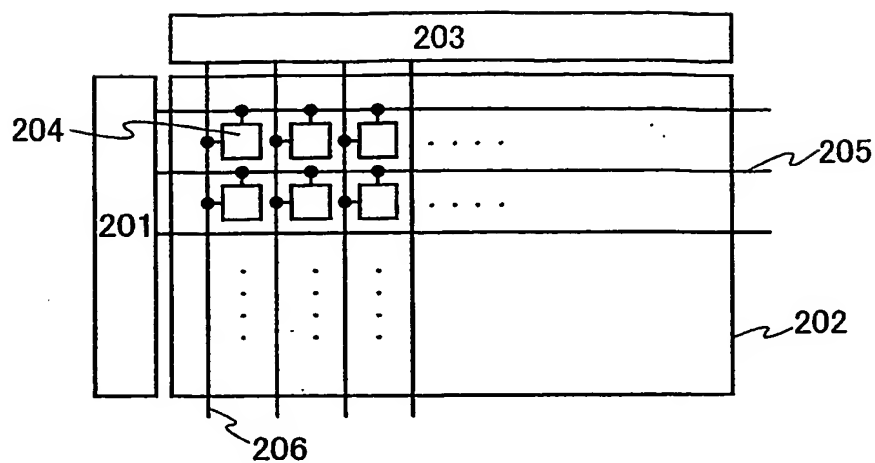


FIG. 2B

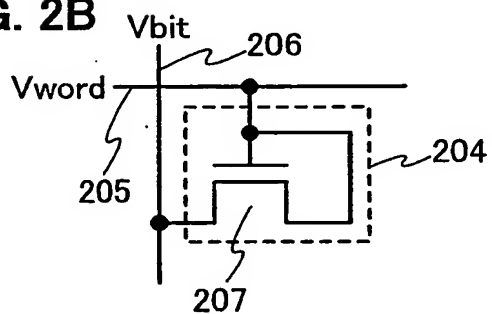
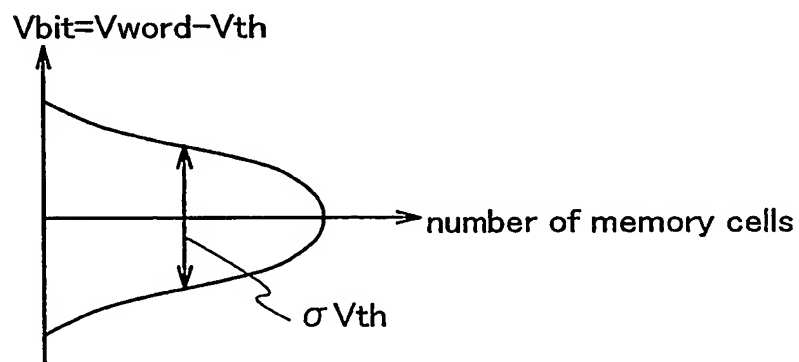


FIG. 2C



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FIG. 3

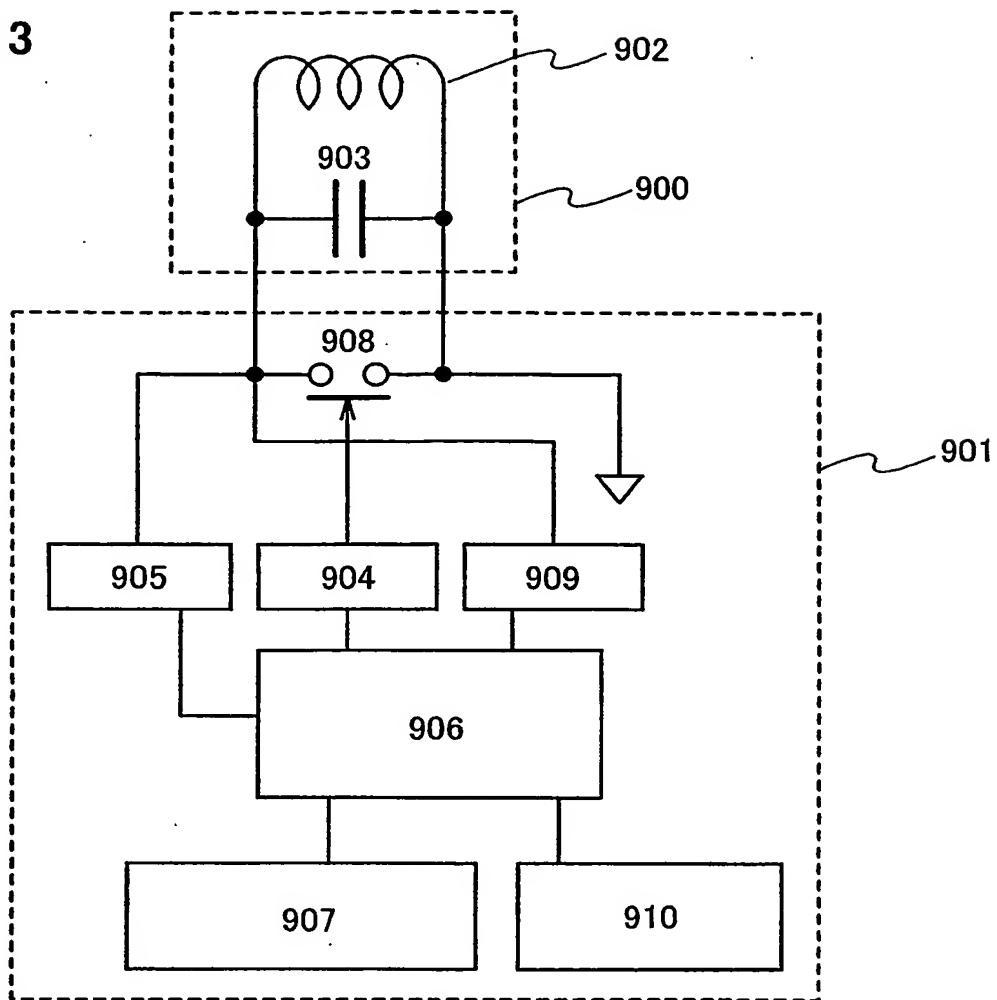
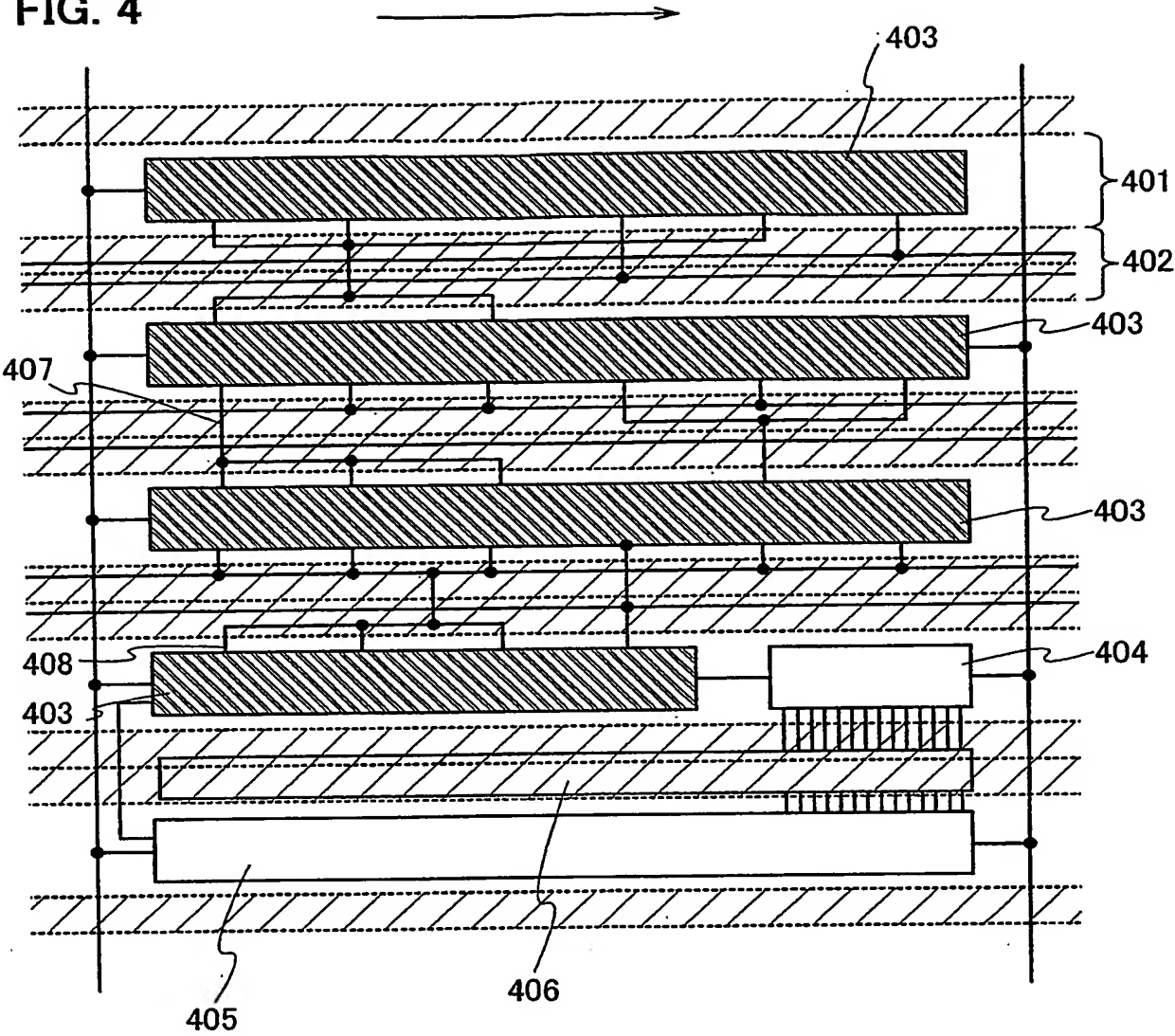


FIG. 4



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FIG. 5A

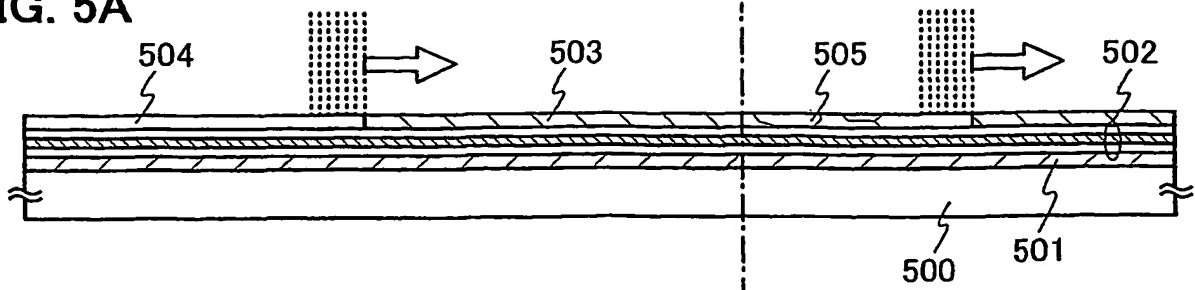


FIG. 5B

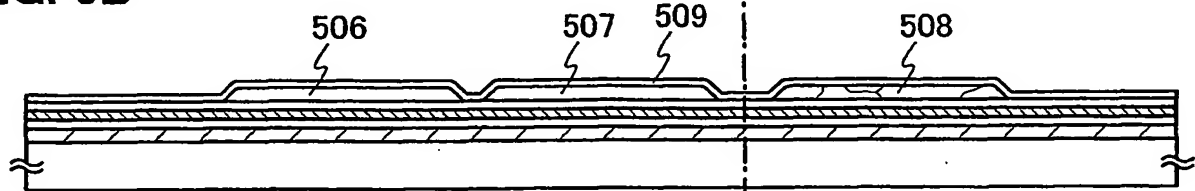


FIG. 5C

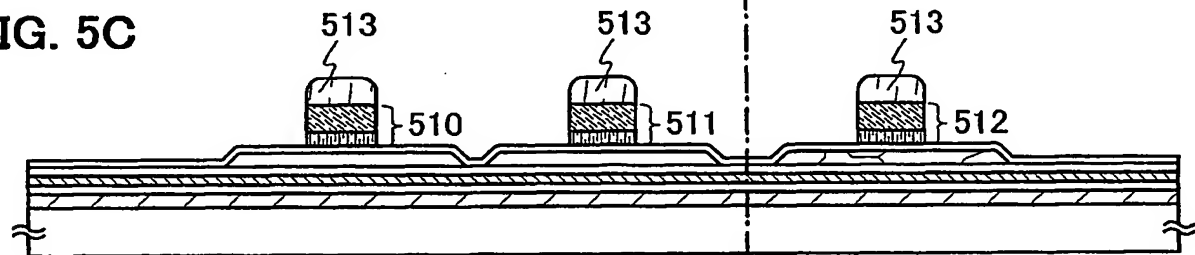


FIG. 5D

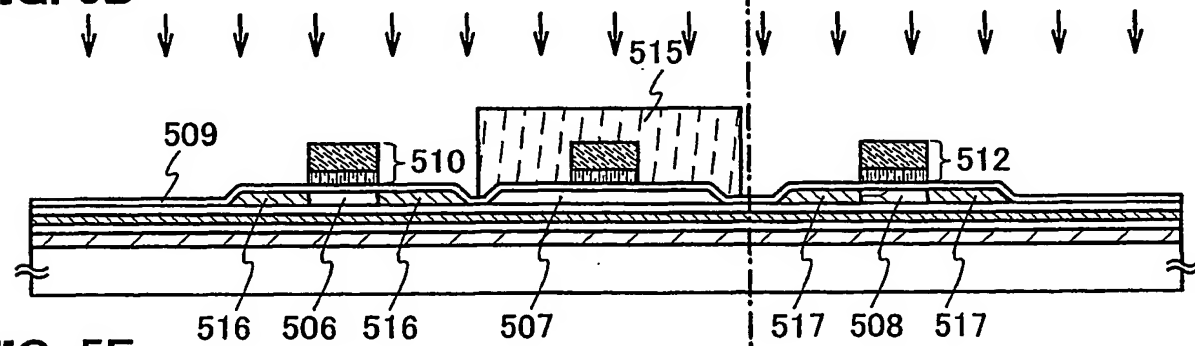
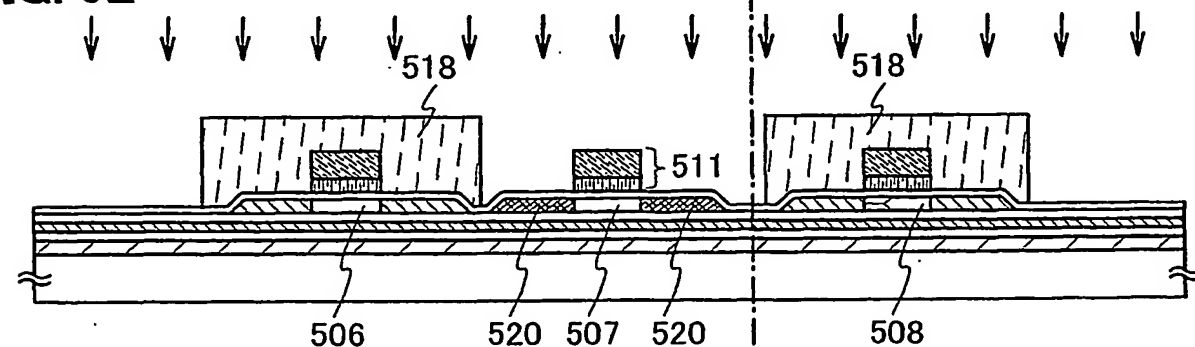


FIG. 5E



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FIG. 6A

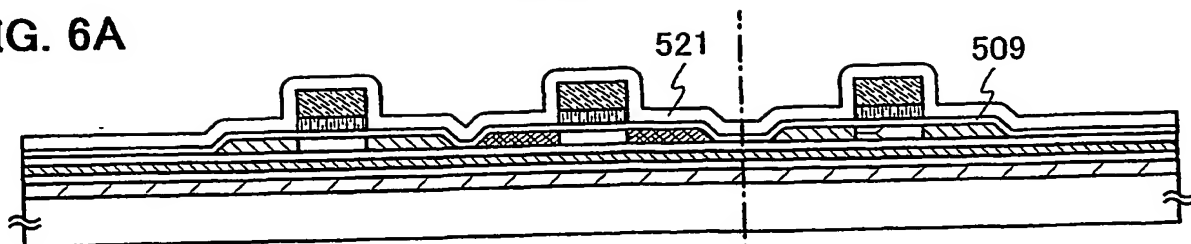


FIG. 6B

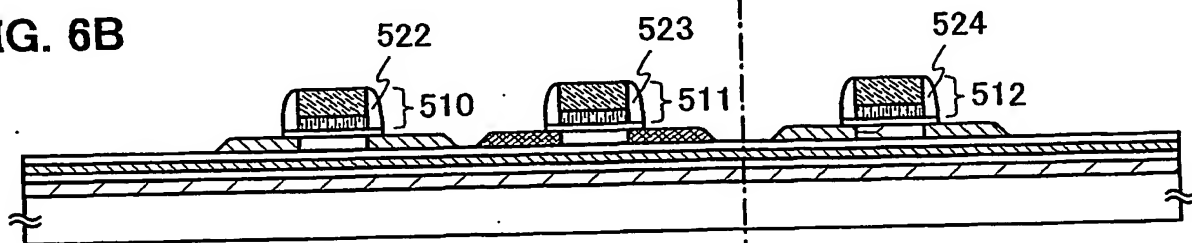


FIG. 6C

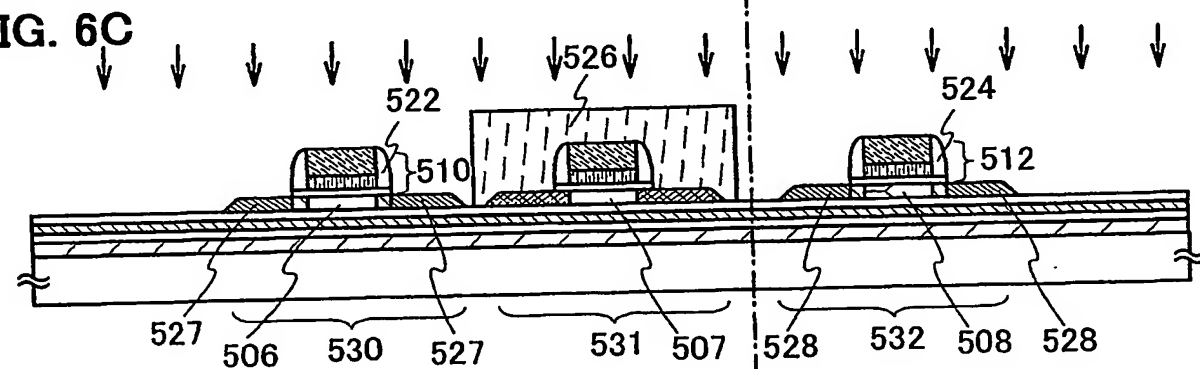


FIG. 6D

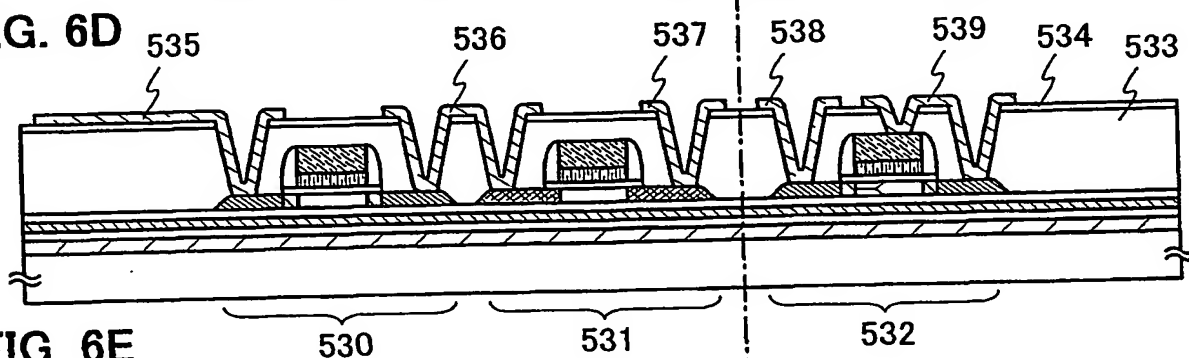
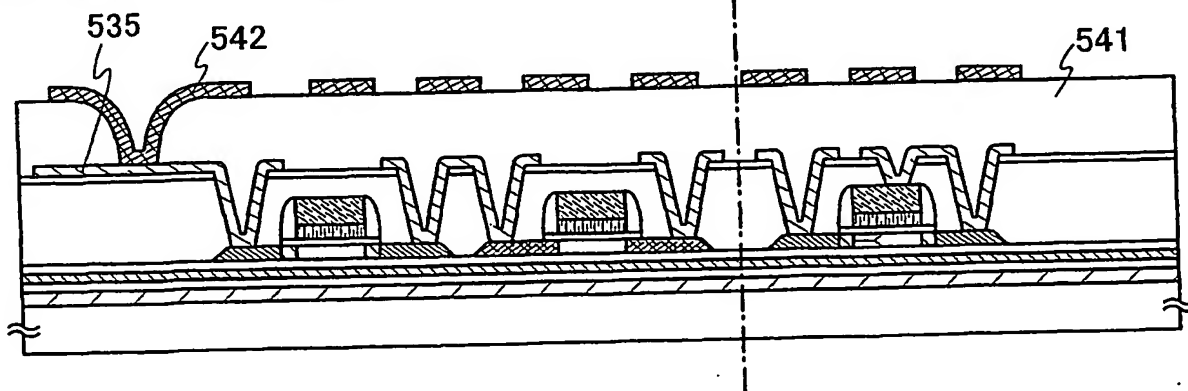


FIG. 6E



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FIG. 7A

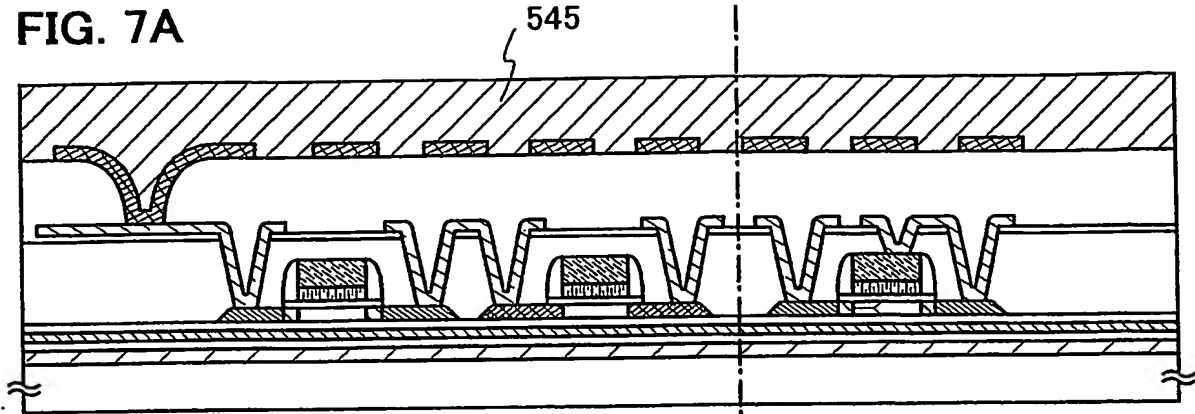


FIG. 7B

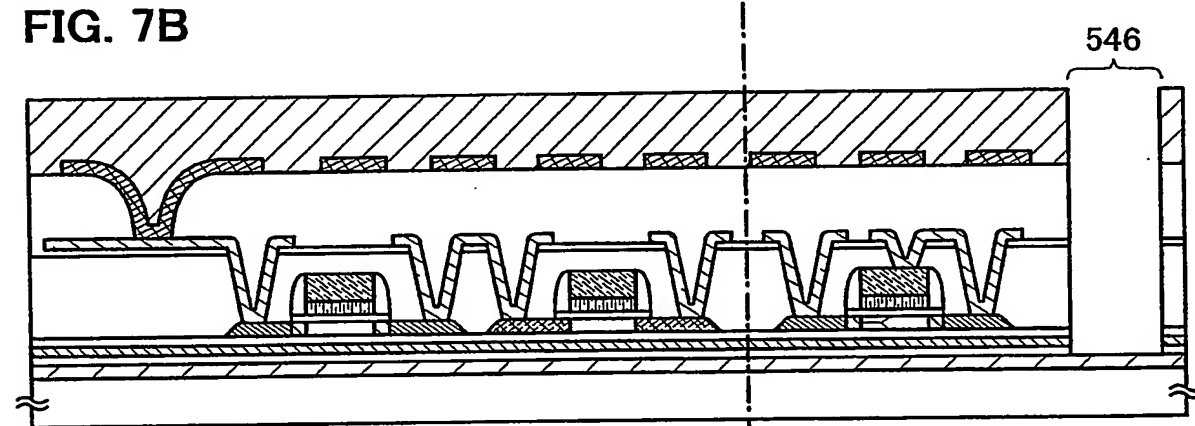
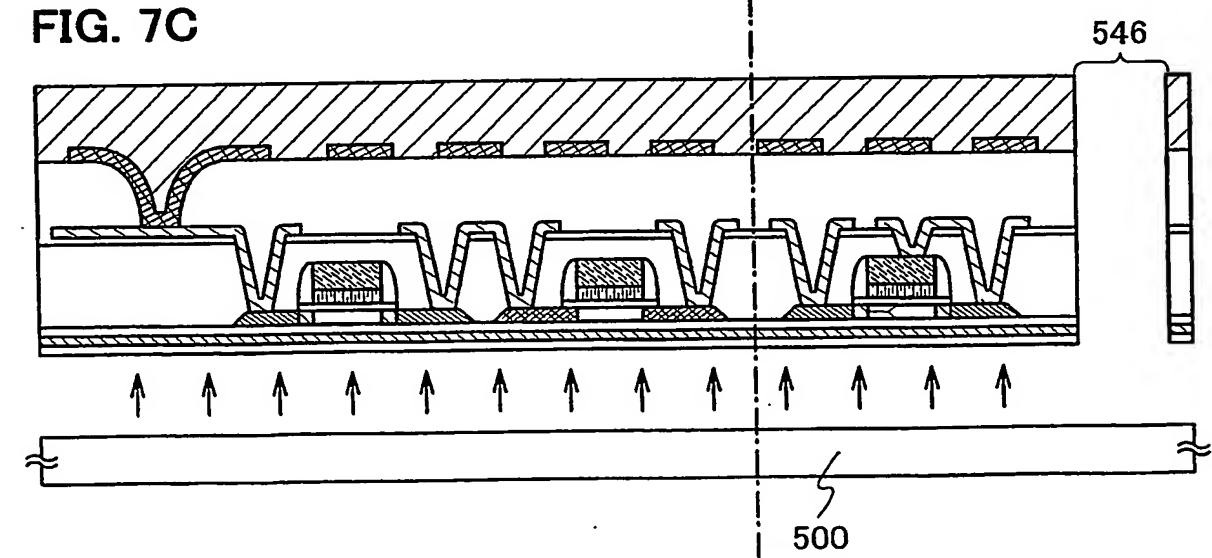


FIG. 7C



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FIG. 8A

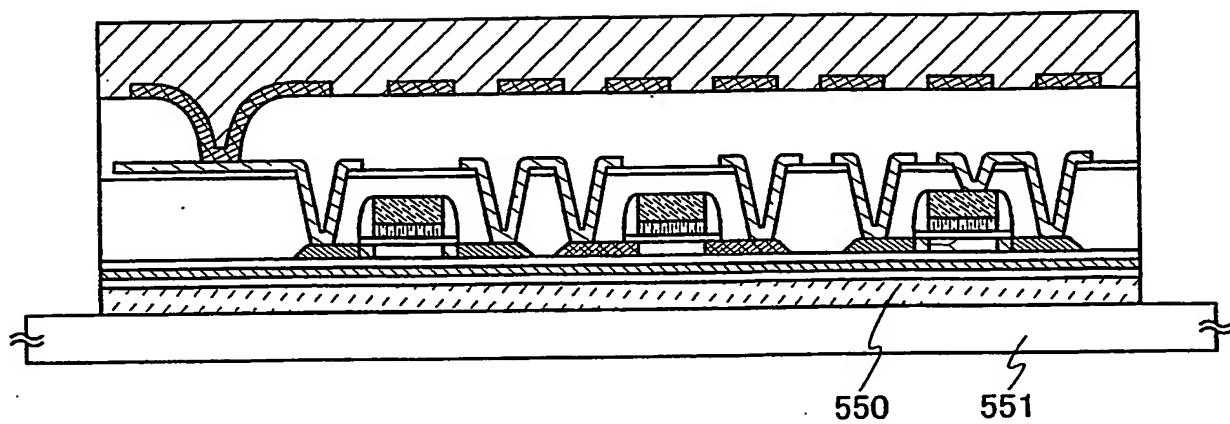
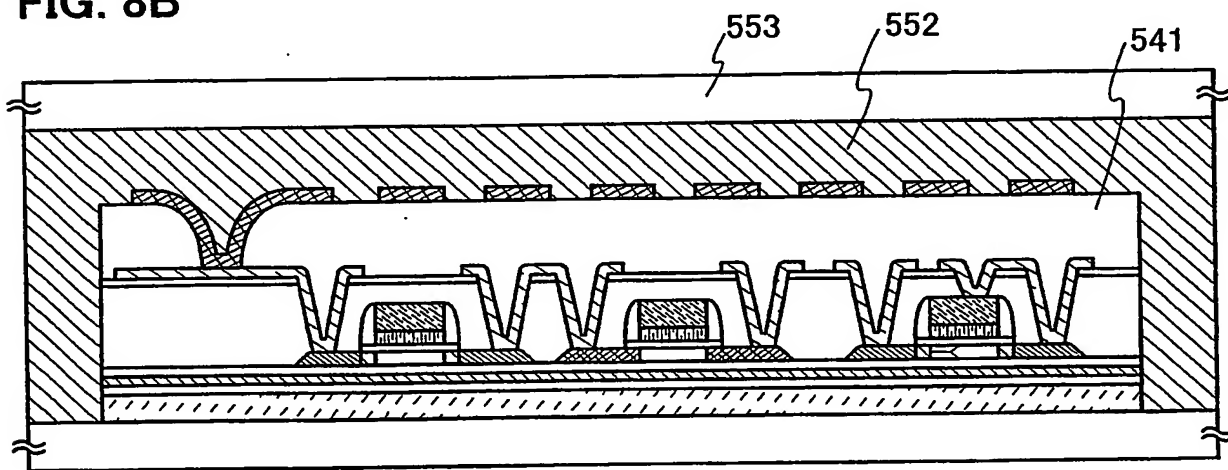
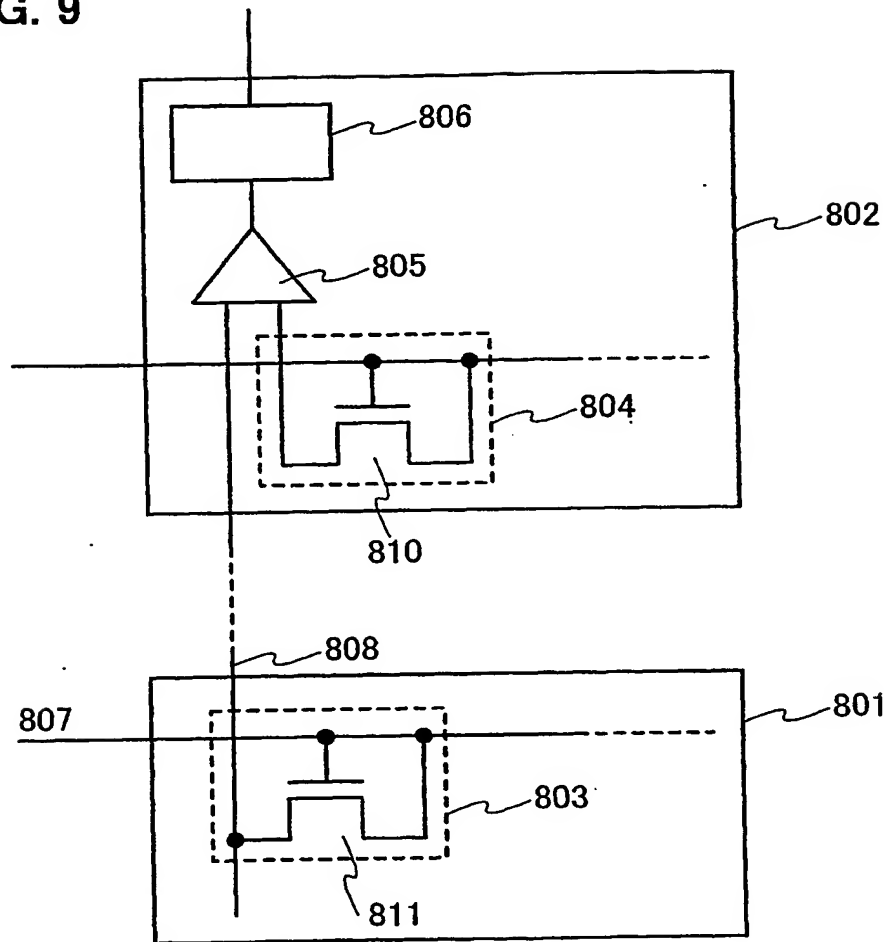


FIG. 8B



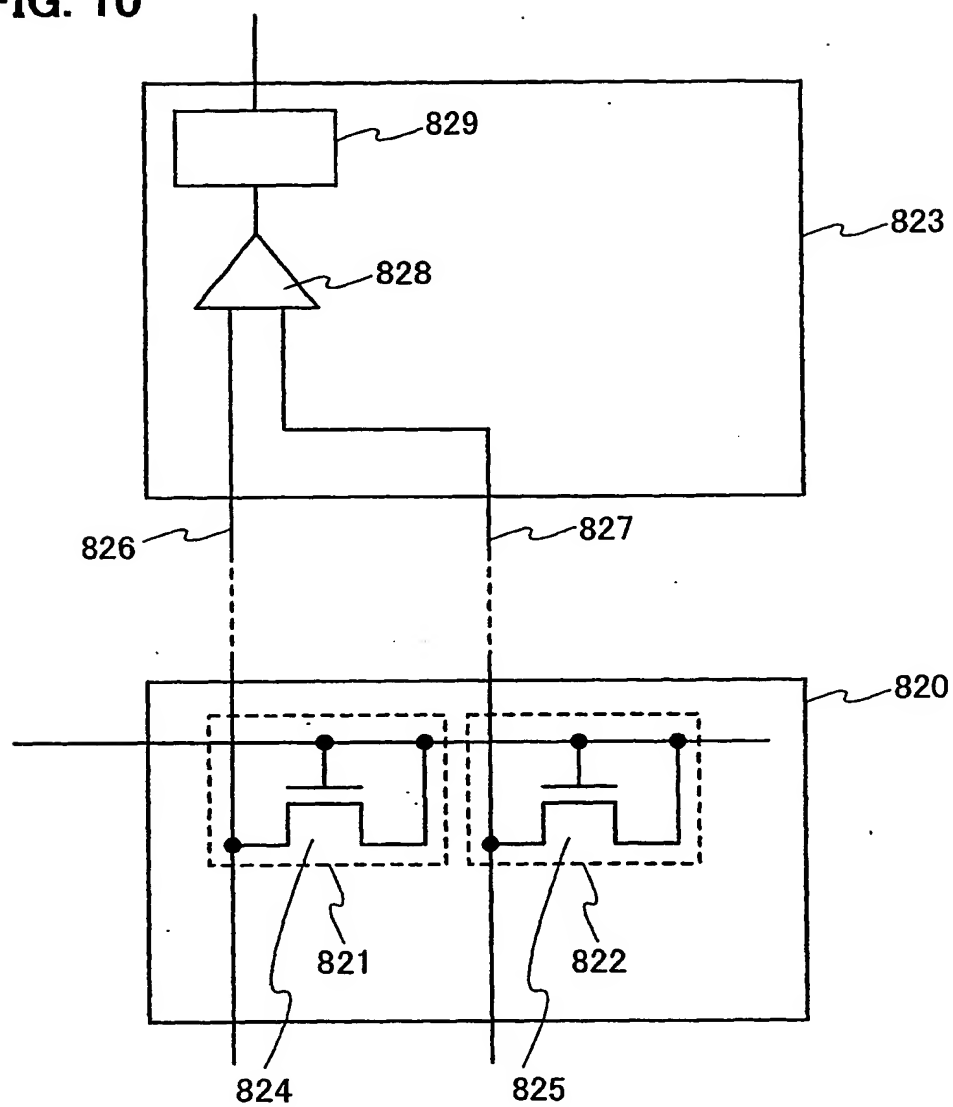
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FIG. 9



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FIG. 10



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FIG. 11

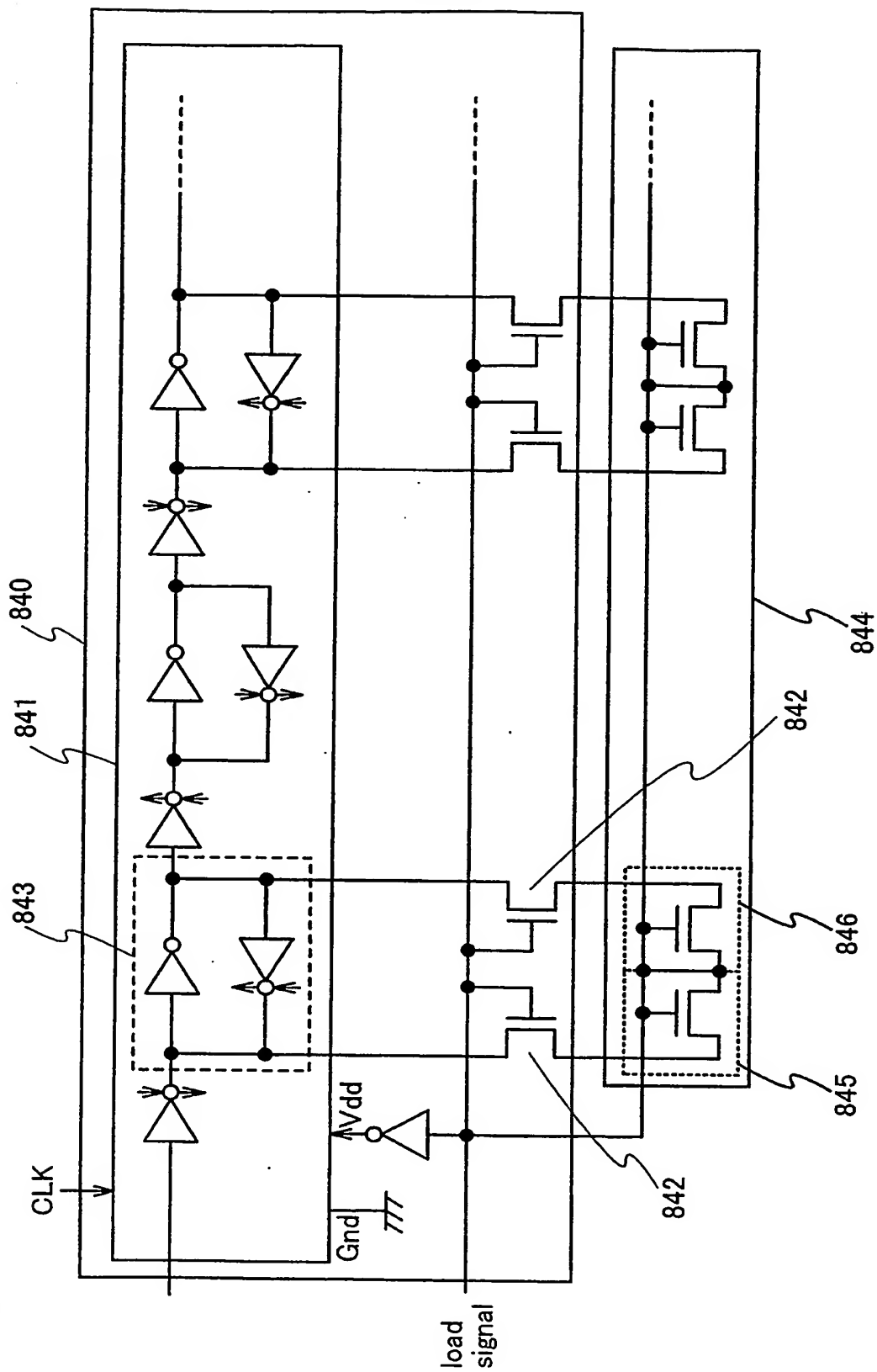


FIG. 12A

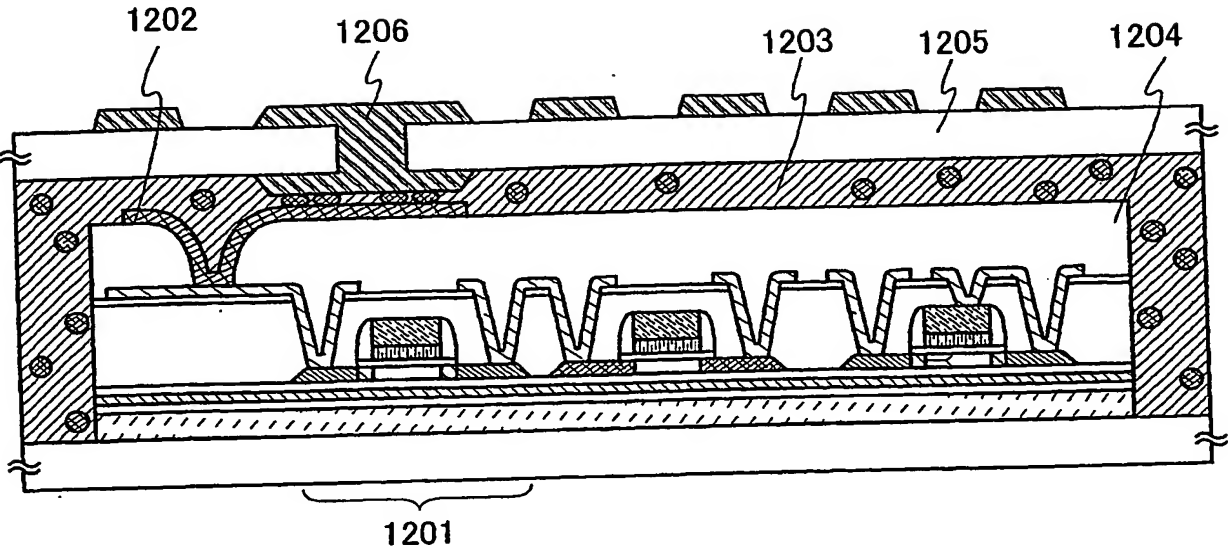


FIG. 12B

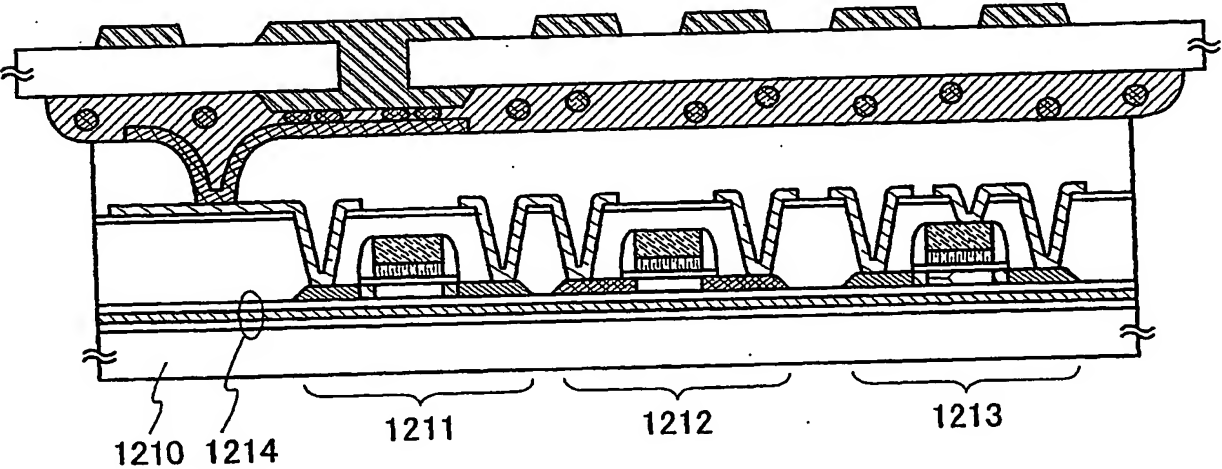


FIG. 13A

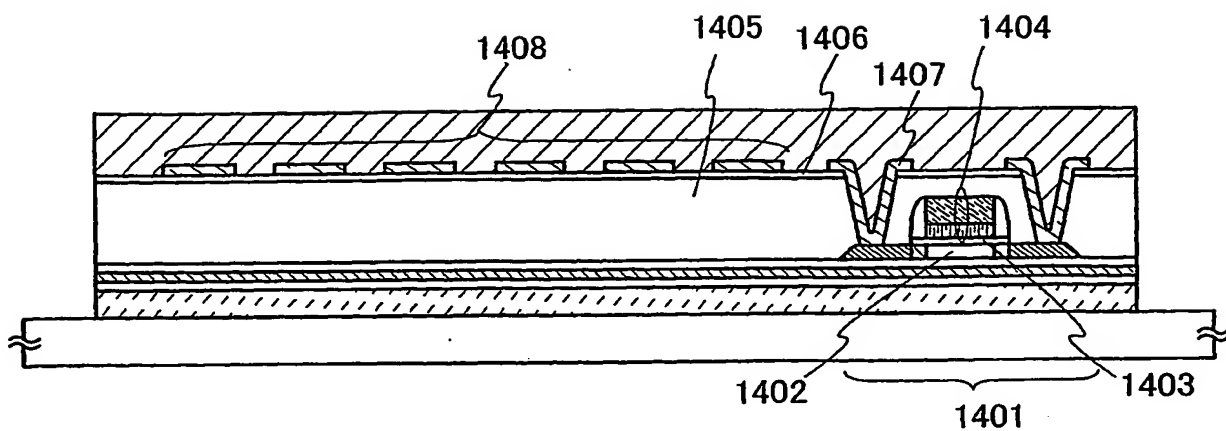


FIG. 13B

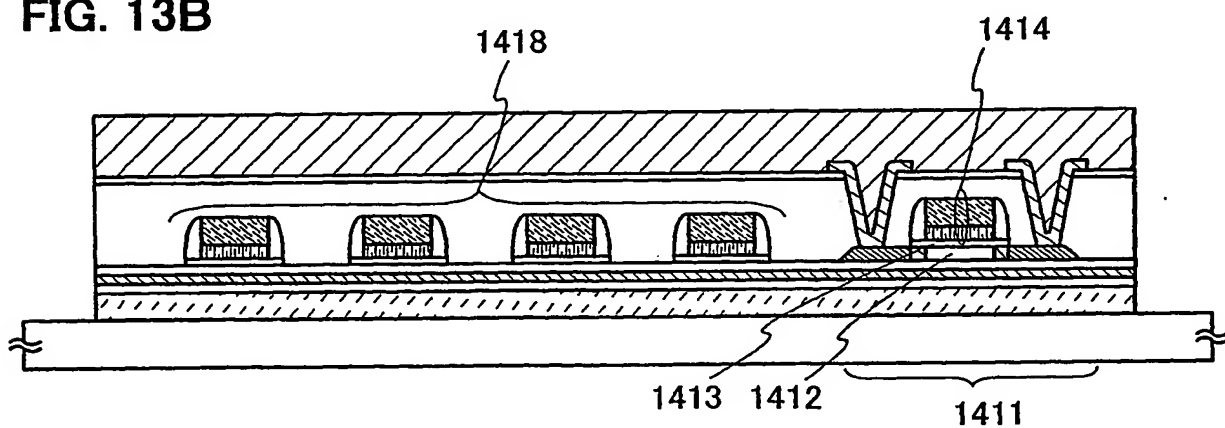


FIG. 14A

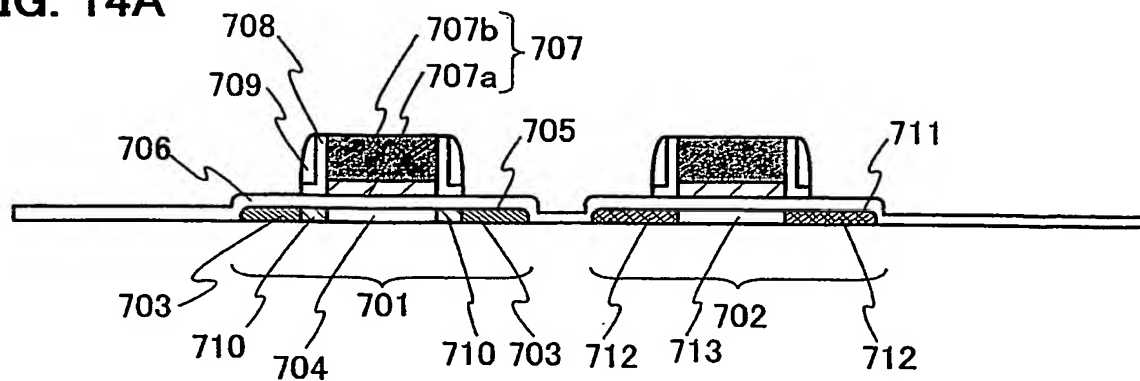


FIG. 14B

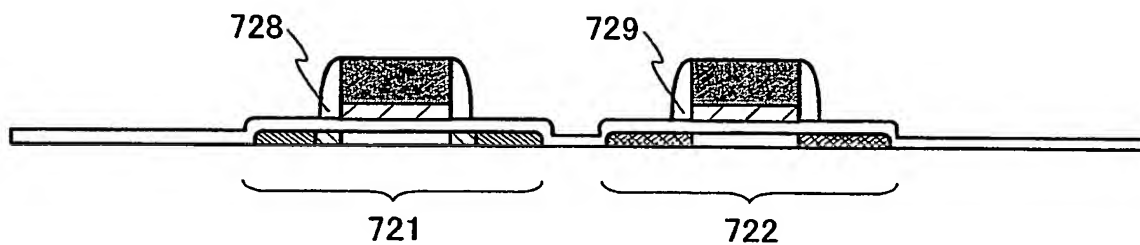
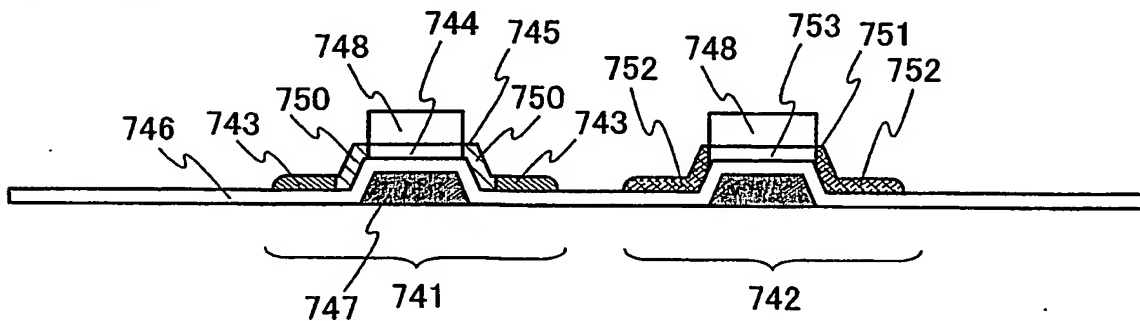


FIG. 14C



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FIG. 15A

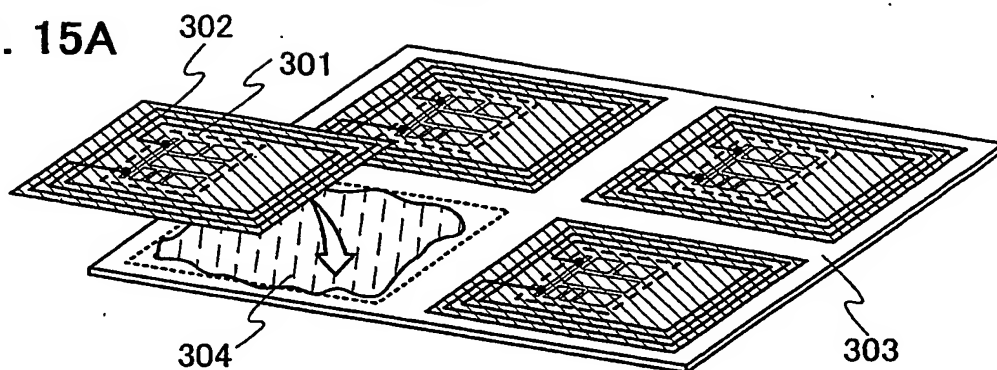


FIG. 15B

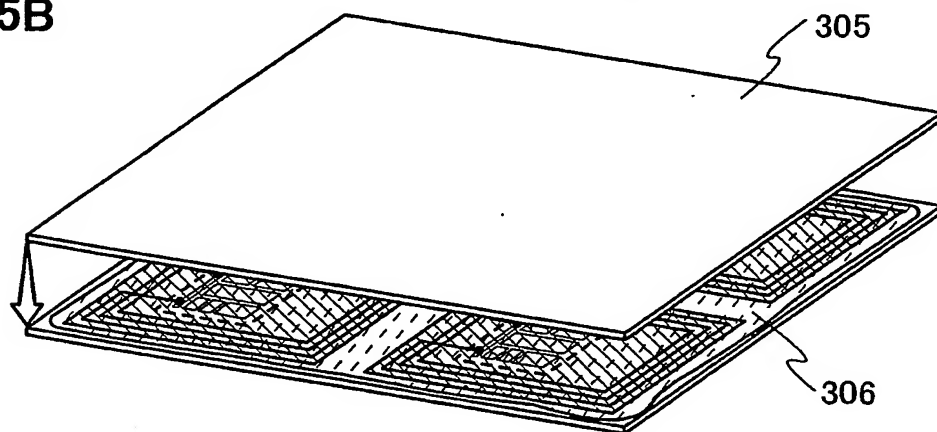


FIG. 15C

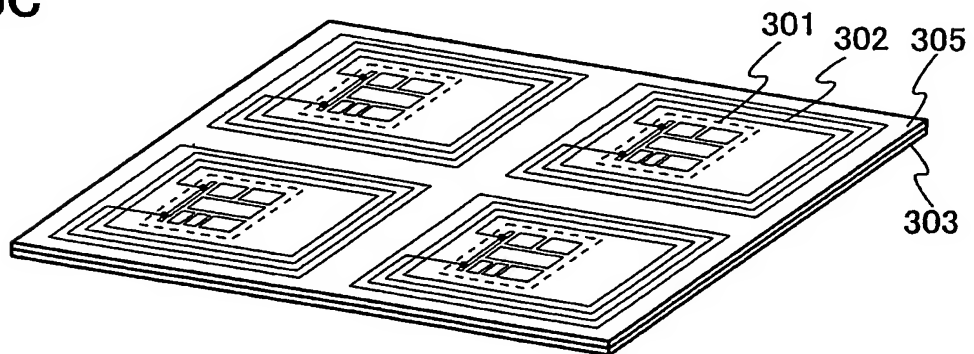
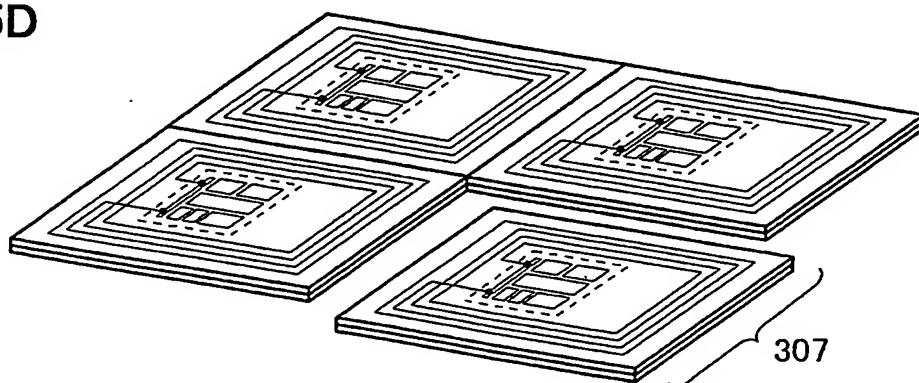


FIG. 15D



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FIG. 16A

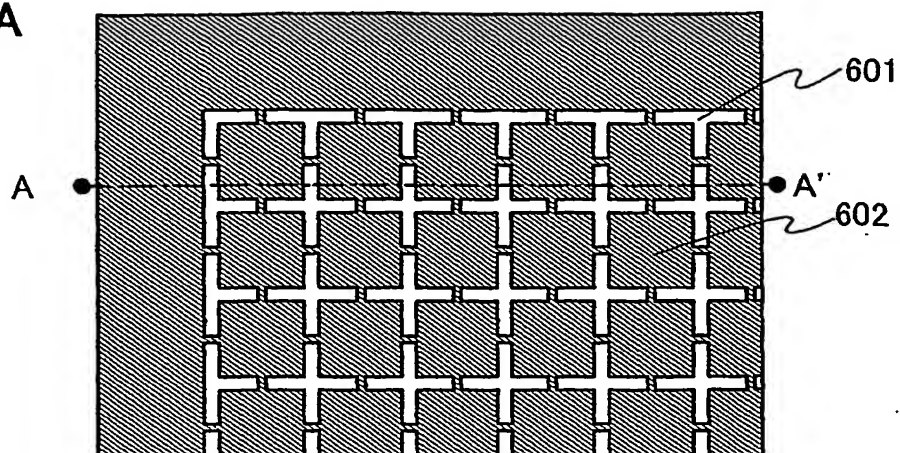


FIG. 16B

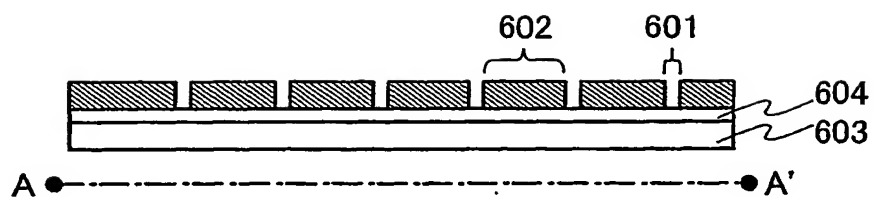


FIG. 16C

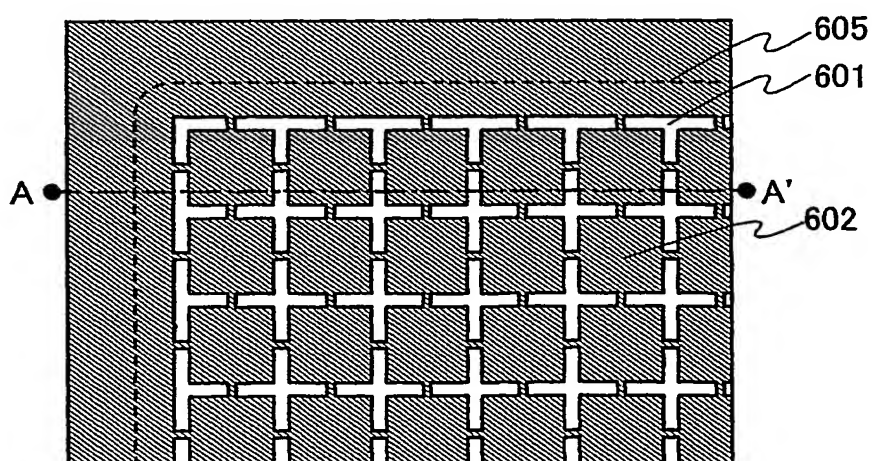


FIG. 16D

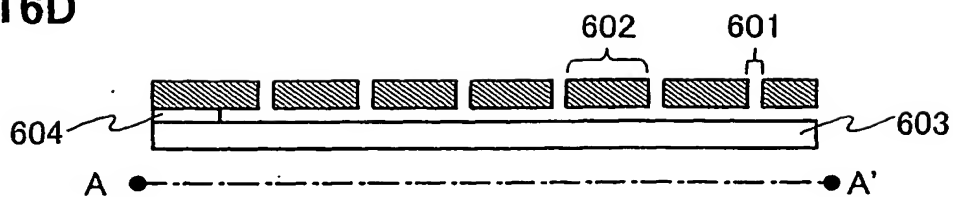


FIG. 17A

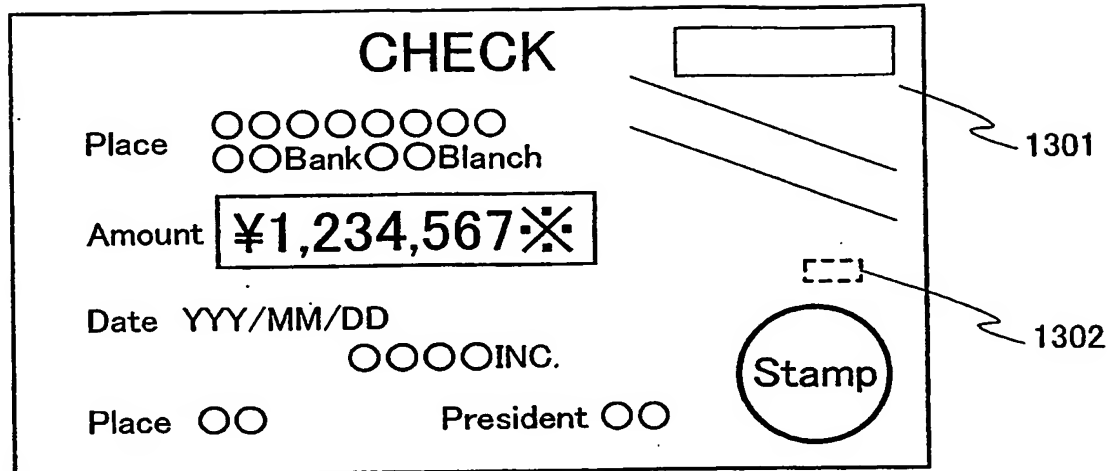


FIG. 17B

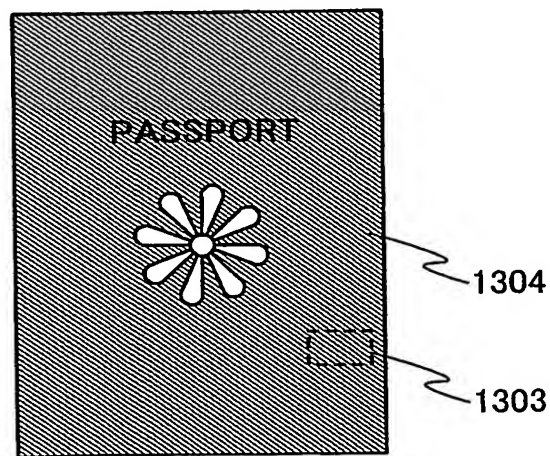
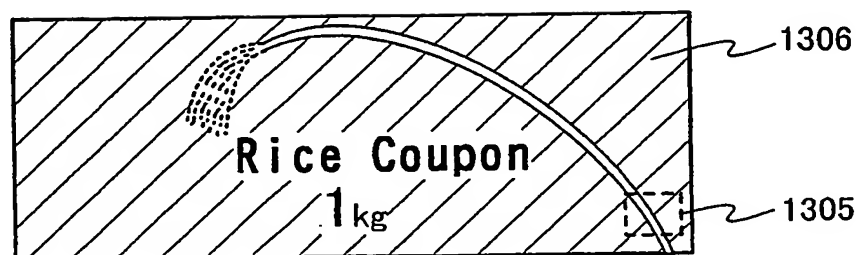


FIG. 17C



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FIG. 18A

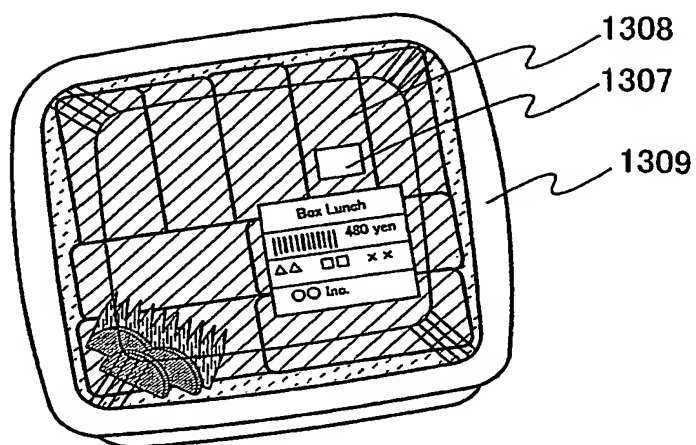


FIG. 18B

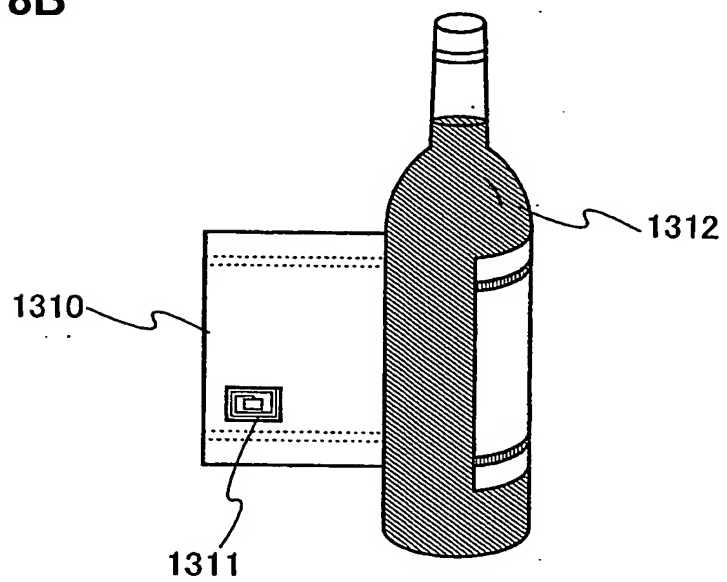
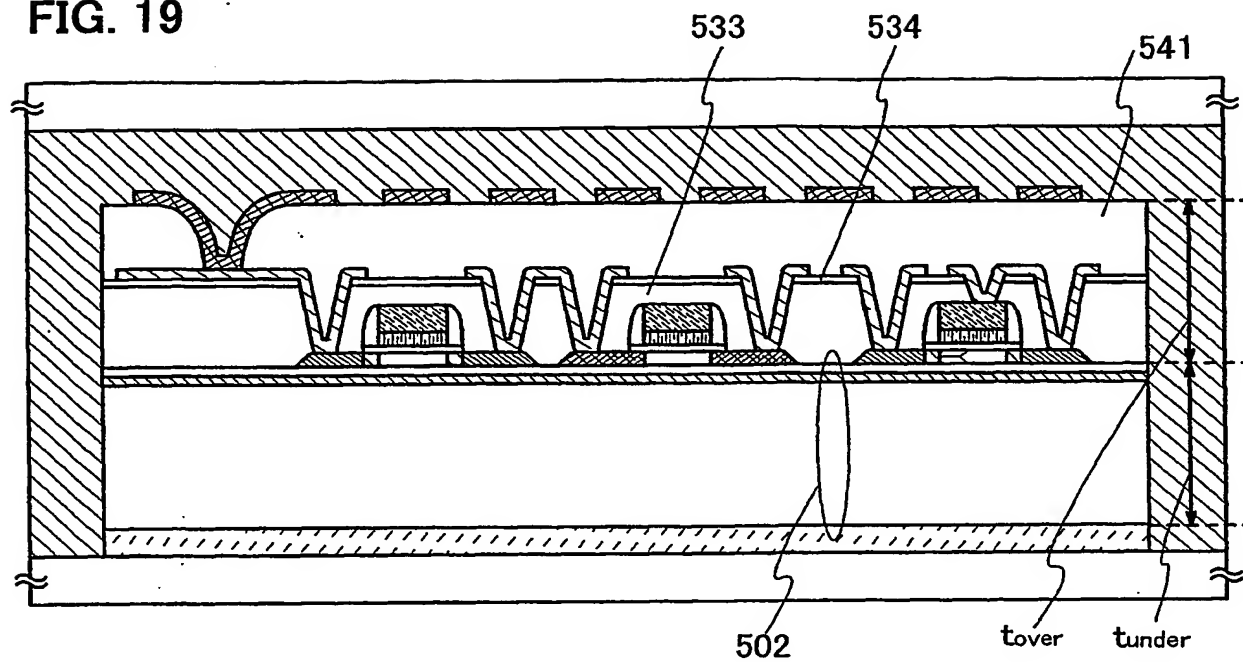


FIG. 19



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FIG. 20A

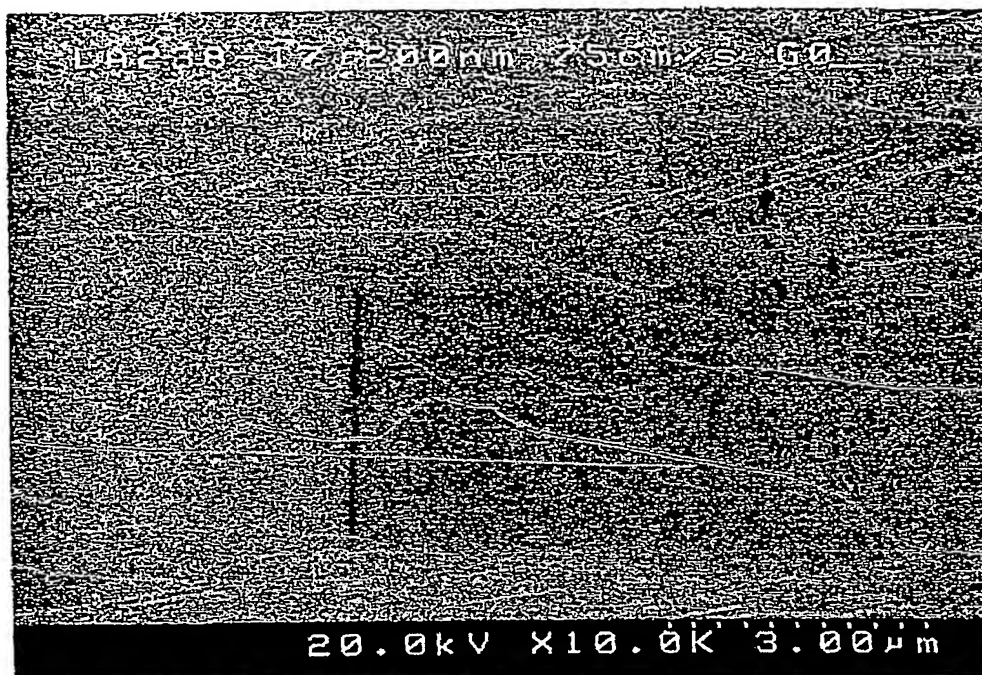


FIG. 20B



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FIG. 21



EXPLANATION OF REFERENCE

- 101: BEAM SPOT, 102: REGION, 103: REGION, 104: ACTIVE LAYER, 105: ACTIVE LAYER, 201: DECODER, 202 MEMORY CELL ARRAY, 203: CIRCUIT, 204: MEMORY CELL, 205: WORD LINE, 206: BIT LINE, 207: TFT, 301: INTEGRATED CIRCUIT, 302 ANTENNA, 303: SUBSTRATE, 304: ADHESIVE AGENT, 305: COVER MEMBER, 306: ADHESIVE AGENT, 307: ID CHIP, 401: REGION, 402: REGION, 403: CIRCUIT, 404: CIRCUIT, 405: DECODER, 406: MEMORY CELL ARRAY, 500: SUBSTRATE, 501: STRIPPING LAYER, 502: BASE FILM, 503: SEMICONDUCTOR FILM, 504: REGION, 505: REGION, 506: SEMICONDUCTOR FILM, 507: SEMICONDUCTOR FILM, 508: SEMICONDUCTOR FILM, 509: GATE INSULATING FILM, 510: GATE ELECTRODE, 511: GATE ELECTRODE, 512: GATE ELECTRODE, 513: RESIST, 515: RESIST, 516: LOW-DENSITY IMPURITY REGION, 518: RESIST, 520: HIGH-DENSITY IMPURITY REGION, 521: INSULATING FILM, 522: SIDE WALL, 526: RESIST, 527: HIGH-DENSITY IMPURITY REGION, 528: HIGH-DENSITY IMPURITY REGION, 530: N-CHANNEL TFT, 531: P-CHANNEL TFT, 532: N-CHANNEL TFT, 533: INTERLAYER INSULATING FILM, 534: INTERLAYER INSULATING FILM, 535: WIRING, 536: WIRING, 538: WIRING, 539: WIRING, 541: INTERLAYER INSULATING FILM, 542: ANTENNA, 545: PROTECTIVE LAYER, 546: GROOVE, 550: ADHESIVE AGENT, 551: SUBSTRATE, 552: ADHESIVE AGENT, 553: COVER MEMBER, 601: GROOVE, 602: INTEGRATED CIRCUIT, 603: SUBSTRATE, 604: STRIPPING LAYER, 605: DOTTED LINE, 701: N-CHANNEL TFT, 702: P-CHANNEL TFT, 703: IMPURITY REGION, 704: CHANNEL-FORMING REGION, 705: SEMICONDUCTOR FILM, 706: GATE INSULATING FILM, 707: GATE ELECTRODE, 707a: CONDUCTIVE FILM, 707b: CONDUCTIVE FILM, 708: SIDEWALL, 709: SIDEWALL, 710: LDD (LIGHTLY DOPED DRAIN) REGION, 711: SEMICONDUCTOR FILM, 712: IMPURITY REGION, 713: CHANNEL-FORMING REGION, 721: N-CHANNEL TFT, 722: P-CHANNEL TFT, 728: SIDEWALL, 741: N-CHANNEL TFT, 742: P-CHANNEL TFT, 743: IMPURITY REGION, 744: CHANNEL-FORMING REGION, 745:

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SEMICONDUCTOR FILM, 746: GATE INSULATING FILM, 747: GATE ELECTRODE, 748: PROTECTIVE FILM, 750: LDD (LIGHTLY DOPED DRAIN) REGION, 751: SEMICONDUCTOR FILM, 752: IMPURITY REGION, 753: CHANNEL-FORMING REGION, 801: MEMORY CELL ARRAY, 802: CIRCUIT, 5 803: MEMORY CELL, 804: REFERENCE MEMORY CELL, 805: DIFFERENTIAL AMPLIFIER CIRCUIT, 806: LATCH CIRCUIT, 807: WORD LINE, 808: BIT LINE, 810: TFT, 811: TFT, 820: MEMORY CELL ARRAY, 821: MEMORY CELL, 823: CIRCUIT, 824: TFT, 826: BIT LINE, 828: DIFFERENTIAL AMPLIFIER CIRCUIT, 829: LATCH CIRCUIT, 840: CIRCUIT, 841: SHIFT REGISTER, 842: SWITCHING 10 ELEMENT, 843: FLIP-FLOP CIRCUIT, 844: MEMORY CELL ARRAY, 845: MEMORY CELL, 900: ANTENNA, 901: INTEGRATED CIRCUIT, 902: ANTENNA COIL, 903: CAPACITOR ELEMENT, 904: MODULATOR CIRCUIT, 905: RECTIFIER CIRCUIT, 906: MICROPROCESSOR, 907: MEMORY, 908: SWITCH, 909: DEMODULATOR CIRCUIT, 910: RANDOM ROM, 1201: TFT, 1202: WIRING, 15 1203: ADHESIVE AGENT, 1204: INTERLAYER INSULATING FILM, 1205: COVER MEMBER, 1206: ANTENNA, 1210: SUBSTRATE, 1211: TFT, 1214: BASE FILM, 1301: CHECK, 1302: ID CHIP, 1303: ID CHIP, 1304: PASS PORT, 1305: ID CHIP, 1306: MERCHANDISE COUPON, 1307: ID CHIP, 1308: PACKAGING MATERIAL, 1309: LUNCH BOX, 1310: LABEL, 1311: ID CHIP, 1312: PRODUCT, 20 1401: TFT, 1402: SEMICONDUCTOR FILM, 1403: GATE INSULATING FILM, 1404: GATE ELECTRODE, 1405: INTERLAYER INSULATING FILM, 1406: INTERLAYER INSULATING FILM, 1407: WIRING, 1408: ANTENNA, 1411: TFT, 1412: SEMICONDUCTOR FILM, 1413: GATE INSULATING FILM, 1414: GATE ELECTRODE, and 1418: ANTENNA.

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